DATA SHEET

74F273A
Octal D flip-flop

Product specification

1996 Mar 12

IC15 Data Handbook

Philips
Semiconductors

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Octal D flip–flop 74F273A

FEATURES

- High impedance inputs for reduced loading (20µA in Low and High states)
- Ideal buffer for MOS microprocessor or memory
- Eight edge–triggered D–type flip–flops
- Buffered common clock
- Buffered asynchronous Master Reset
- See 74F377A for clock enable version
- See 74F373 for transparent latch version
- See 74F374 for 3–State version

DESCRIPTION

The 74F273 has eight edge–triggered D–type flip–flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ($\overline{MR}$) inputs load and reset (clear) all flip–flops simultaneously.

The register is fully edge–triggered. The state of each D input, one setup time before the Low–to–High clock transition, is transferred to the corresponding flip–flop's Q output.

All outputs will be forced Low independently of Clock or Data inputs by a Low voltage level on the $\overline{MR}$ input. The device is useful for applications where the true output only is required and the CP and $\overline{MR}$ are common to all elements.

TYPE	TYPICAL f_{MAX}	TYPICAL SUPPLY CURRENT (TOTAL)
74F273A	170MHz	25mA

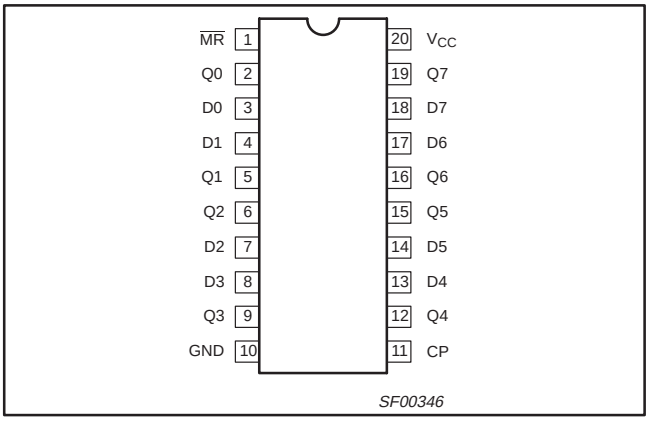
ORDERING INFORMATION

PACKAGES	COMMERCIAL RANGE V_{CC} = 5V±10%; T_{amb} = 0°C to +70°C	PKG. DWG. #
20–pin plastic DIP	74F273AN	SOT146-1
20–pin plastic SOL	74F273AD	SOT163-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

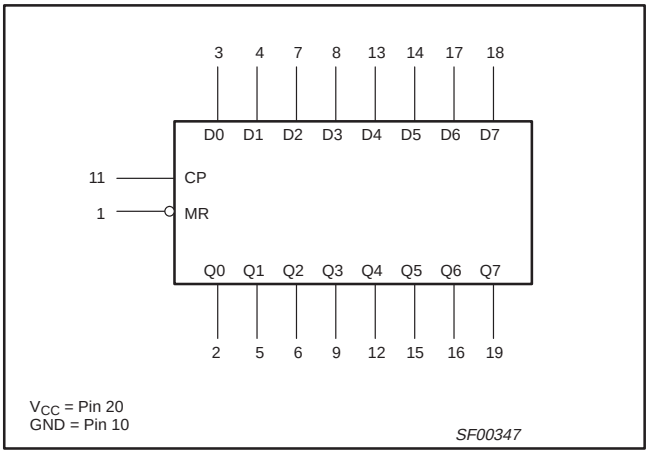
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 – D7	Data inputs	1.0/0.033	20µA/20µA
$\overline{MR}$	Master Reset input (active–Low)	1.0/0.033	20µA/20µA
CP	Clock pulse input (active rising edge)	1.0/0.033	20µA/20µA
Q0 – Q7	Data outputs	50/33	1.0mA/20mA

PIN CONFIGURATION



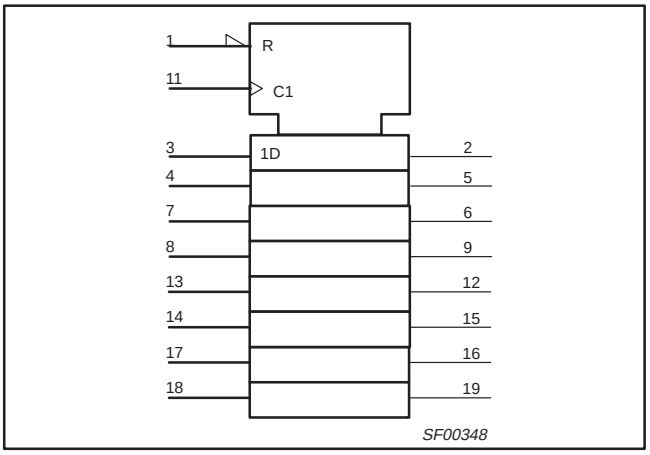
SF00346

LOGIC SYMBOL

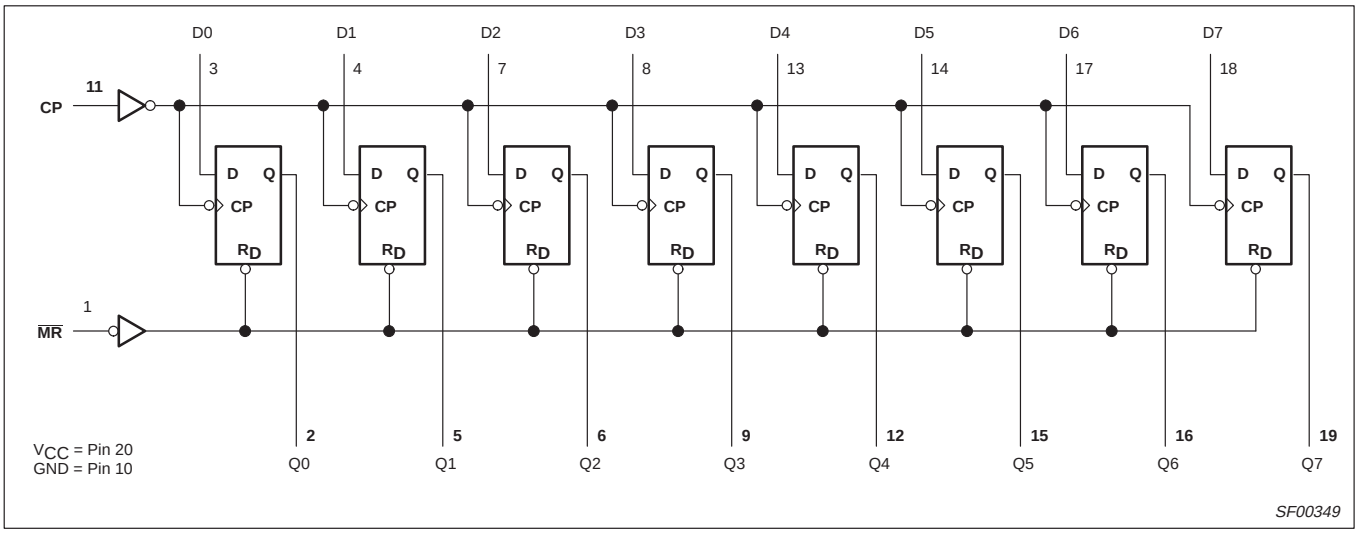


SF00347

LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



FUNCTION TABLE

INPUTS			OUTPUTS	OPERATING
$\overline{MR}$	CP	Dn	Q0 – Q7	MODE
L	X	X	L	Reset (clear)
H	↑	h	H	Load ”1”
H	↑	l	L	Load ”0”

H = High voltage level
h = High voltage level one set–up time prior to the Low–to–High clock transition
L = Low voltage level
l = Low voltage level one set–up time prior to the Low–to–High clock transition
X = Don’t care
↑ = Low–to–High clock transition

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	–0.5 to +7.0	V
V_{IN}	Input voltage	–0.5 to +7.0	V
I_{IN}	Input current	–30 to +5	mA
V_{OUT}	Voltage applied to output in High output state	–0.5 to V_{CC}	V
I_{OUT}	Current applied to output in Low output state	40	mA
T_{amb}	Operating free air temperature range	0 to +70	°C
T_{stg}	Storage temperature range	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	TYP	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High–level input voltage	2.0			V
V_{IL}	Low–level input voltage			0.8	V
I_{Ik}	Input clamp current			–18	mA
I_{OH}	High–level output current			–1	mA
I_{OL}	Low–level output current			20	mA
T_{amb}	Operating free air temperature range	0		+70	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIONS[1]		LIMITS MIN	LIMITS TYP[2]	LIMITS MAX	UNIT
V_{OH}	High-level output voltage	MR & CP inputs	V_{CC} = MIN, V_{IL} = 0.0V[3], V_{IH} = 4.5V[3], I_{OH} = MAX	±10%V_{CC}	2.5			V
				±5%V_{CC}	2.7	3.4		V
		other inputs	V_{CC} = MIN, V_{IL} = MAX, V_{IH} = MIN, I_{OH} = MAX	±10%V_{CC}	2.5			V
				±5%V_{CC}	2.7	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IL} = MAX, V_{IH} = MIN, I_{OH} = MAX	±10%V_{CC}		0.30	0.50	V
				±5%V_{CC}		0.30	0.50	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = I_{IK}			–0.73	-1.2	V
I_I	Input current at maximum input voltage		V_{CC} = 0.0V, V_I = 7.0V				100	µA
I_{IH}	High–level input current		V_{CC} = MAX, V_I = 2.7V				20	µA
I_{IL}	Low–level input current		V_{CC} = MAX, V_I = 0.5V				–20	µA
I_{OS}	Short–circuit output current[4]		V_{CC} = MAX		-60		-150	mA
I_{CC}	Supply current (total)	I_{CCH}	V_{CC} = MAX			24	38	mA
		I_{CCL}				27	43	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
2. All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
3. To reduce the effect of external noise during test.
4. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

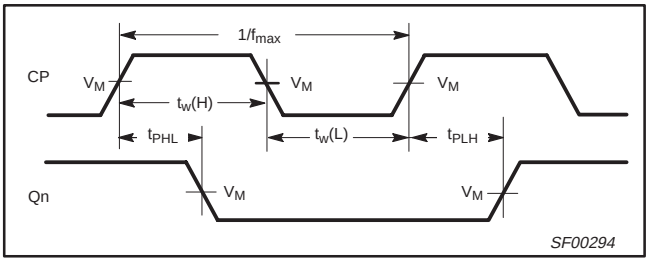
AC CHARACTERISTICS FOR 'F273A

SYMBOL	PARAMETER	WAVEFORM	LIMITS T_{amb} = +25°C, V_{CC} = +5.0V, C_L = 50pF, R_L = 500Ω Min	Typ	Max	LIMITS T_{amb} = 0°C to +70°C, V_{CC} = +5.0V ±10%, C_L = 50pF, R_L = 500Ω Min	Max	UNIT
f_{MAX}	Maximum clock frequency	1	150	170		125		MHz
t_{PLH} t_{PHL}	Propagation delay CP to Qn	1	3.5 5.0	5.0 7.0	8.0 9.5	3.0 4.5	9.0 10.0	ns
t_{PHL}	Propagation delay $\overline{MR}$ to Qn	2	5.0	7.0	9.0	5.0	9.5	ns

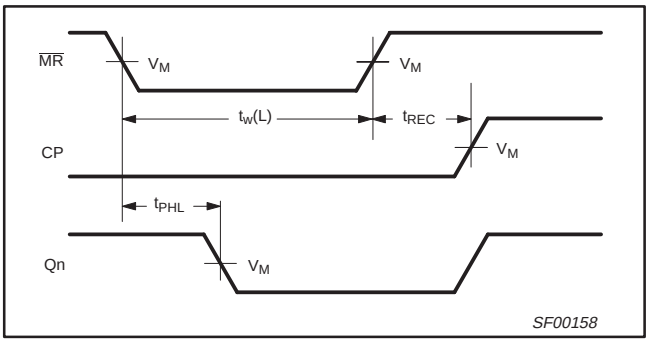
AC SETUP REQUIREMENTS FOR ’F273A

SYMBOL	PARAMETER	WAVEFORM	LIMITS					UNIT
			T_{amb} = +25°C, V_{CC} = +5.0V, C_L = 50pF, R_L = 500Ω			T_{amb} = 0°C to +70°C, V_{CC} = +5.0V ±10%, C_L = 50pF, R_L = 500Ω		
			Min	Typ	Max	Min	Max	
$t_s(H)$ $t_s(L)$	Setup time, High or Low Dn to CP	3	3.0 2.0			2.5 2.5		
$t_h(H)$ $t_h(L)$	Hold time, High or Low Dn to CP	3	0.5 0.0			2.5 1.0		ns
$t_w(H)$ $t_w(L)$	Clock pulse width High or Low	1	4.5 3.5			5.0 4.0		ns
$t_w(L)$	Master Reset pulse width, Low	2	3.0			3.5		ns
t_{REC}	Recovery time $\overline{MR}$ to CP	2	4.0			5.0		ns

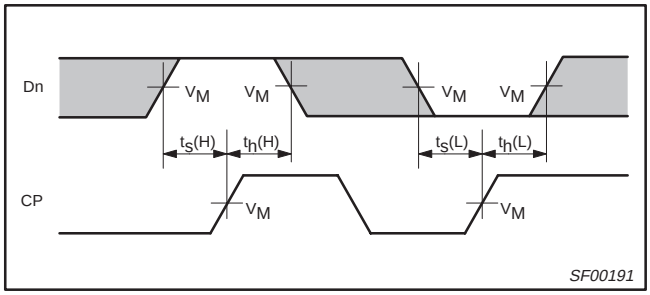
AC WAVEFORMS



Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



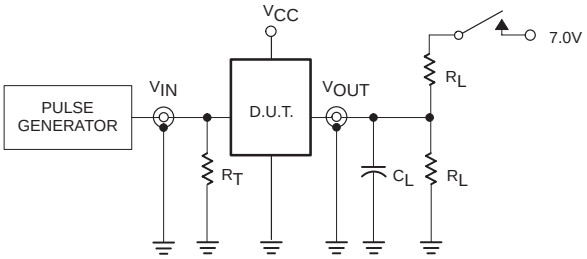
Waveform 2. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock Recovery Time



Waveform 3. Data Setup and Hold Times

NOTE: For all waveforms, V_M = 1.5V.
The shaded areas indicate when the input is permitted to change for predictable output performance.

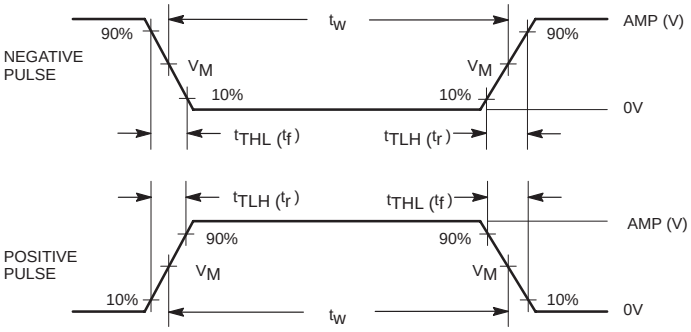
TEST CIRCUIT AND WAVEFORMS



Test Circuit for Open Collector Outputs

SWITCH POSITION

TEST	SWITCH
t_{PLZ}	closed
t_{PZL}	closed
All other	open



Input Pulse Definition

DEFINITIONS:

R_L = Load resistor; see AC electrical characteristics for value.

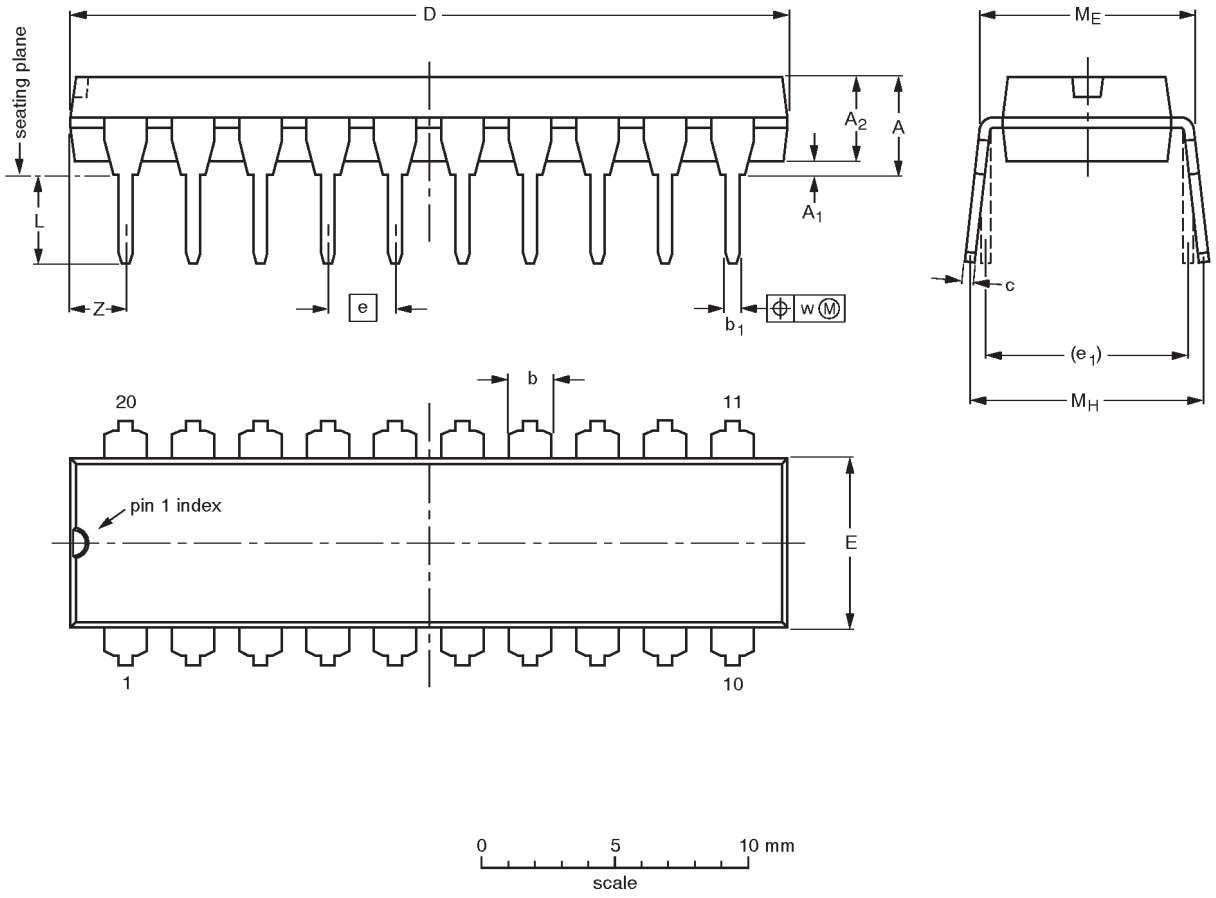
C_L = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

family	INPUT PULSE REQUIREMENTS					
	amplitude	V_M	rep. rate	t_w	t_{TLH}	t_{THL}
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns

SF00128

DIP20: plastic dual in-line package; 20 leads (300 mil) **SOT146-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

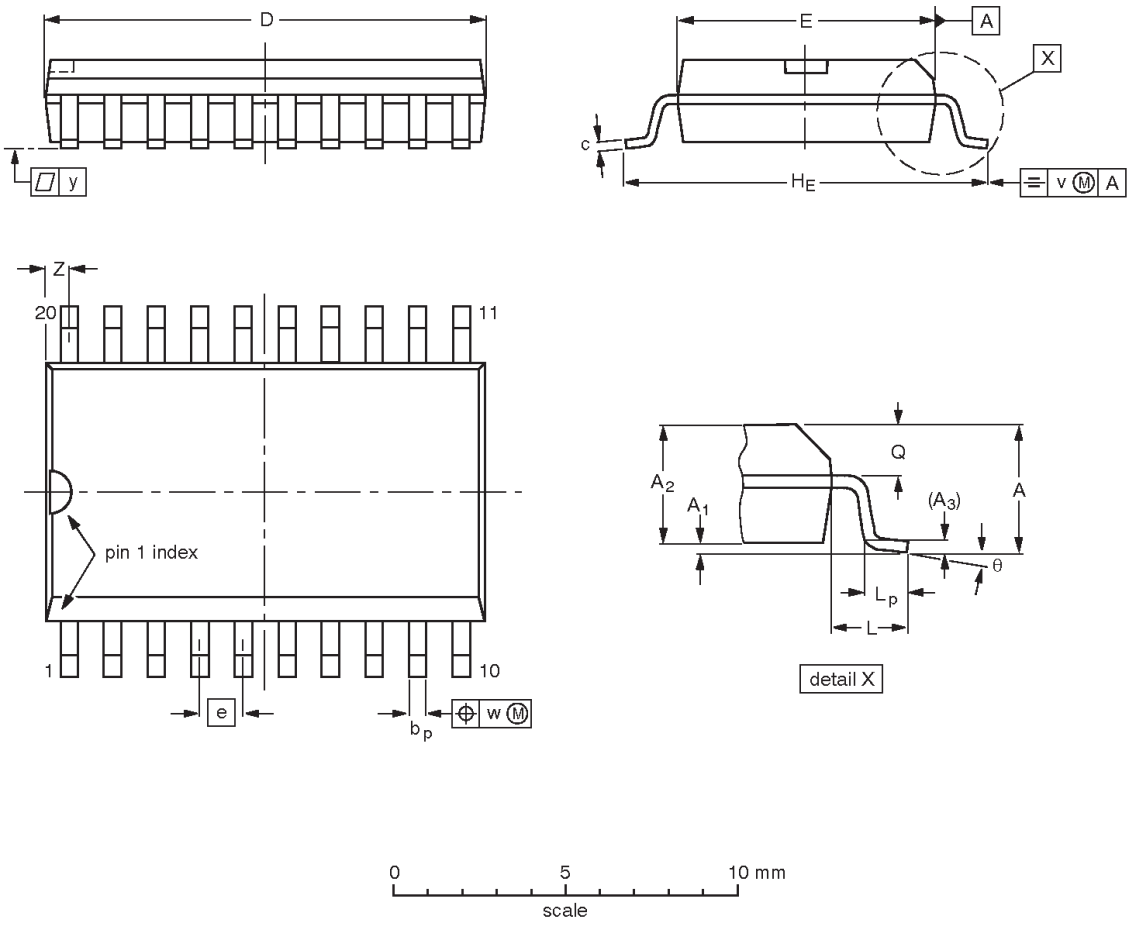
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			~~92-11-17~~ 95-05-24

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				~~95-01-24~~ 97-05-22

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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